



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

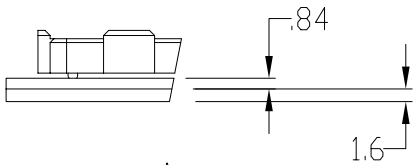
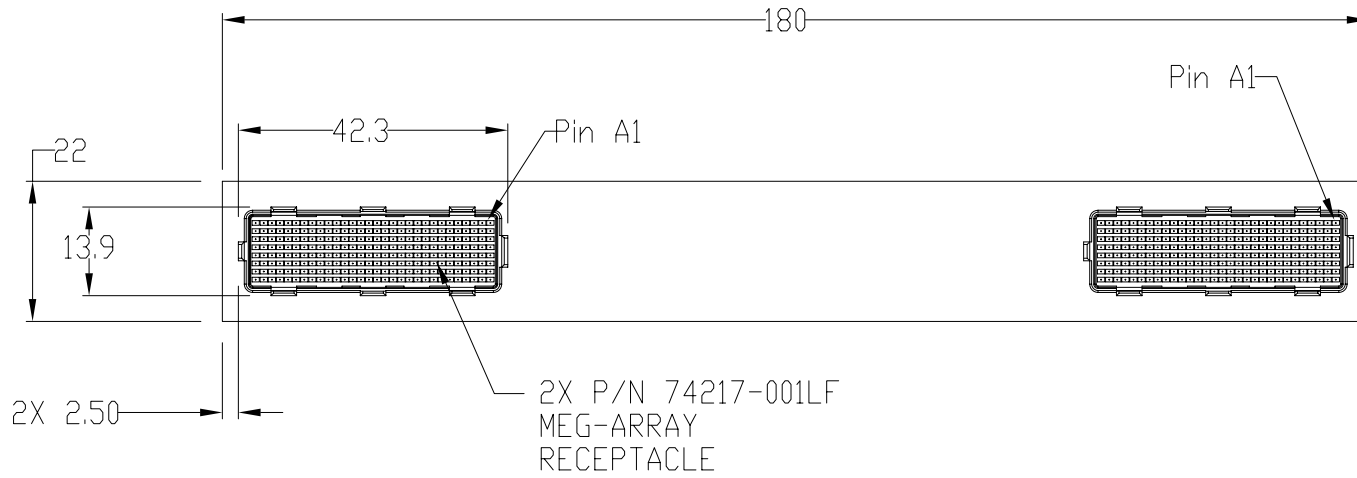
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PRODUCT NUMBER
10061262-001LF



DETAIL A
SCALE 2:1

mat'l. code SEE NOTES				surface ASME Y14.5		tolerance ASME Y14.5		projection MM		product family	
tolerances unless otherwise specified				angle B		.X ±.3		MM		title	
A	V06-0065	DAI	01/25/06	.XX ±.10		scale 1:1		FLEX CIRCUIT W/240 POS. MEG-ARRAY RECEPTACLE ASSEMBLIES			
B	V06-0112	DAI	02/06/06	0' ±2'		FCI		dwg no		sheet 1 of 2	
C	V07-0276	DAI	2007-04-05	dr D.INGRAM 01/25/06		eng D.BRANN 01/25/06		10061262		size A4	
				chr D.BRANN 01/25/06		appd D.BRANN 01/25/06		type		CUSTOMER Drawing	
sheet index	revision sheet	c	c								
		1	2								

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NOTES:

1. MATERIAL:

- HOUSING: LCP
- CONTACT: COPPER ALLOY
- CONTACT PLATING: 38µm (15µ in) Au OVER Ni
- SOLDER BALL PLATING: SnAgCu
- BACKER BOARD: G-10
- FLEX CIRCUIT: Polyimide

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHEMENT.

3. LEAD FREE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

4. FOR PROPER APPLICATION, FOLLOW FCI APPLICATION SPECIFICATION GS-20-033.

5. CONSTRUCTION PER IPC-6013 CLASS II TYPE 3 OR 4.

6. MEG-ARRAY PRODUCT SPECIFICATION: GS-12-100.

Cover coat
1/2 OZ Copper
Adhesive
Polyimide



.81/.84

A

A

B

B

mat'l. code SEE NOTES		surface ASME Y14.5	tolerance ASME Y14.5	projection 	product family
ltr	ecn no dr date	tolerances unless otherwise specified		MM	title FLEX CIRCUIT W/240 POS. MEG-ARRAY RECEPTACLE ASSEMBLIES
c		angle 0° ±2'	.X ±.3 .XX ±.10 .XXX ±.050		
		dr	D.INGRAM	01/25/06	dwg no 10061262 sheet 2 of A4 type CUSTOMER Drawing
		eng	D.BRANN	01/25/06	
		chr	D.BRANN	01/25/06	
		appd	D.BRANN	01/25/06	
sheet index	revision sheet				